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MaxLinear Expands AI Infrastructure Control-Plane Portfolio with Intelligent eFuse Solutions for Rack-Scale Power Protection and Telemetry

- *New MxL745950 and MxL745951P address growing hyperscaler demand for intelligent power protection and telemetry solutions and will be showcased at the OCP APAC 2026 Summit booth PL33*

CARLSBAD, Calif.--(BUSINESS WIRE)-- MaxLinear, Inc. (NASDAQ: MXL), a leader in high-performance analog, mixed-signal and connectivity semiconductor solutions, today announced the expansion of its AI infrastructure portfolio with two new 16V high-current electronic fuse (eFuse) solutions, the MxL745950 and MxL745951P. AI infrastructure is driving unprecedented increases in rack power density, power-domain complexity, and serviceability requirements. The devices are designed to help hyperscalers, OEMs, ODMs, and networking equipment providers protect, monitor, and manage critical power paths across AI servers, accelerator trays, data center switches, fan trays, power shelves, plug-in modules, and rack-scale platforms.

This press release features multimedia. View the full release here:
<https://www.businesswire.com/news/home/20260810522477/en/>

MaxLinear's MxL745950 and MxL745951P intelligent eFuse solutions help enable scalable power protection, telemetry, and fault isolation for next-generation AI infrastructure.

As AI clusters scale from server-centric deployments to rack-scale systems,

power-path protection is becoming a mission-critical element of platform reliability. MaxLinear's new eFuse portfolio brings together integrated hot-swap protection, scalable high-current operation, compact implementation, and intelligent monitoring to help customers improve uptime, isolate faults, accelerate root-cause analysis, and gain deeper visibility into power-domain behavior across large-scale AI deployments.

Industry demand for AI infrastructure continues to accelerate. Market research estimates that data center semiconductor revenue will reach approximately \$843 billion by 2030. Hyperscaler capital spending is also rising sharply as operators expand AI compute capacity to support training, inference, and emerging agentic workloads. These trends are increasing the need for highly reliable power protection, telemetry, and serviceability across servers, networking systems, accelerator platforms, and rack-level infrastructure. Industry estimates place the global eFuse market at approximately \$1.0B today, with growth expected through 2030 as electronic systems require more intelligent, compact, resettable, and programmable

power protection. When viewed together with adjacent hot-swap and intelligent power-path protection ICs used in data center, telecom, automotive, and industrial infrastructure, the broader opportunity expands into a multi-billion-dollar power-protection market.

The **MxL745950** is a 16V, 50A electronic fuse with 1mΩ on-resistance in a compact 5mm × 5mm LGA-32 package. It integrates current sensing, temperature monitoring, fault indication, programmable soft-start and parallel-operation capability for higher-current applications, such as servers, networking systems, and plug-in modules.

The **MxL745951P** is a 16V, 60A stackable eFuse with 0.79mΩ on-resistance, PMBus™/I²C interface support, high-precision telemetry, configurable protection thresholds, non-volatile fault recording, and active current balancing during start-up and steady-state operation. The device provides digital telemetry for input voltage, input current, input energy, output voltage, output current, input power, and output power, enabling platform designers to add more intelligent power monitoring and fault visibility in AI and high-performance computing infrastructure.

“As AI infrastructure scales, the opportunity is expanding beyond compute silicon into the control, power, and telemetry technologies required to operate dense racks reliably,” said Amit D. Bavisi, Ph.D., Senior Vice President and General Manager, Analog Mixed-Signal Business Unit at MaxLinear. “Our new eFuse solutions extend MaxLinear’s role across AI servers, accelerator trays, switches, fan trays, power shelves, and rack-level platforms by helping customers build more observable, serviceable, and resilient power architectures.”

Why AI Infrastructure Requires Intelligent Power Protection

- **Rack-level fault isolation:** Integrated protection and fault-management capabilities help isolate subsystem failures before they impact broader rack operation.
- **Operational visibility:** High-precision telemetry and fault recording help operators improve power-domain visibility and accelerate root-cause analysis.
- **Scalable current handling:** Parallel operation and active current balancing support increasingly dense AI platforms and higher-current accelerator deployments.
- **Serviceability and uptime:** Hot-swap and inrush-control capabilities help support maintenance and replacement workflows in live or service-sensitive infrastructure.
- **Control-plane integration:** Complements MaxLinear’s AI infrastructure portfolio spanning connectivity, monitoring, rack management, console access, telemetry, power management, and protection.

Optimized for AI Data Center Power Protection

- **High-current capability:** Up to 50A for MxL745950 and up to 60A for MxL745951P per device, with parallel operation support for higher-current applications.
- **Low-loss integrated power path:** Integrated MOSFETs with low on-resistance help reduce power loss and voltage droop in dense systems.
- **Hot-swap and inrush control:** Programmable or configurable soft-start helps limit inrush current during card insertion and backplane hot-plug events.
- **Robust protection:** Integrated UVP, OVP, OCP, SCP, OTP, MOSFET fault diagnosis, and fault reporting improve system protection and status visibility.
- **Advanced telemetry and configurability:** MxL745951P adds PMBus/I²C telemetry, configurable thresholds and timers, black-box fault recording, and NVM-based custom

configuration storage.

- **Compact footprint:** 5mm × 5mm LGA-32 and 5mm × 4.5mm VQFN-26L packages support space-constrained board designs.

Product Summary

Product	Positioning	Key Specifications	Monitoring / interface	Package
MxL745950	16V/50A eFuse for servers, networking, plug-in modules, and compact power-path protection	4V to 16V input; up to 50A; 1mΩ RDS(ON)	Analog current sensing, temperature monitoring, fault indication	5mm × 5mm LGA-32
MxL745951P	16V/60A stackable eFuse for server/HPC, data center switches/routers, accelerator trays, and fan trays	2.9V to 16V input; up to 60A; 0.79mΩ RDS(ON)	PMBus/I ² C telemetry, ±1% current monitoring accuracy, black-box fault recording, NVM configuration	5mm × 4.5mm VQFN-26L

OCP APAC 2026 Demonstration and Availability

MaxLinear will introduce its new eFuse portfolio at the 2026 OCP APAC Summit, taking place August 11-12, 2026 at TaiNEX2 in Taipei City, Taiwan. The MxL745950 and MxL745951P will be showcased at Booth PL33, alongside MaxLinear's broader AI infrastructure portfolio for rack-scale management, connectivity, telemetry, power management, and protection. Customer meetings will be held in Meeting Room 4.

The MxL745950 and MxL745951P are sampling now with volume production expected in Q4 2026. Visit [maxlinear.com/mxl745950](https://www.maxlinear.com/mxl745950) and [maxlinear.com/mxl745951P](https://www.maxlinear.com/mxl745951P) for more information. Customers interested in evaluating the new eFuse solutions can contact MaxLinear for additional product information and availability details.

Product status	Event alignment	Booth
Sampling now; Production in Q4 2026	OCP APAC Summit, Aug. 11-12, 2026	TaiNEX2, Taipei City, PL33 and Meeting Room 4

About MaxLinear, Inc.

MaxLinear, Inc. (Nasdaq: MXL) is a leading provider of radio frequency (RF), analog, digital, and mixed-signal integrated circuits for access and connectivity, wired and wireless infrastructure, and industrial and multimarket applications. MaxLinear is headquartered in Carlsbad, California. For more information, please visit <https://www.maxlinear.com/>.

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Cautionary Note About Forward-Looking Statements

This press release contains forward-looking statements within the meaning of Section 27A of the Securities Act of 1933, as amended, and Section 21E of the Securities Exchange Act of 1934, as amended. Forward-looking statements include, among others, statements relating to MaxLinear's new eFuse products, the MxL745950 and MxL745951P, and the functionality, performance, benefits, and availability of such products, including the

expectation that the products will reach volume production in the fourth quarter of 2026 and will be demonstrated at the OCP APAC 2026 Summit; statements about the potential market opportunity for intelligent eFuse and power-path protection solutions, including the estimated size and growth of the AI server market, the global eFuse market, and the broader power-protection market described in this release; the potential growth of the AI market and hyperscaler capital spending; and statements by MaxLinear's Senior Vice President and General Manager, Analog Mixed-Signal Business Unit. These forward-looking statements involve known and unknown risks, uncertainties, and other factors that may cause actual results to be materially different from any future results expressed or implied by the forward-looking statements and our future financial performance and operating results forecasts generally. Forward-looking statements are based on management's current, preliminary expectations and are subject to various risks and uncertainties. In particular, our future operating results are substantially dependent on our assumptions about market trends and conditions. Additional risks and uncertainties affecting our business, future operating results and financial condition include, without limitation; risks relating to: the development, testing, and commercial introduction of new products and product functionalities, including the new MxL745950 and MxL745951P eFuse products; risks related to the market opportunity for intelligent eFuse and power-path protection solutions, including the market estimates described above, not developing or being smaller or slower to develop than anticipated, or MaxLinear not being able to capture share of the market; the capabilities of our technology; our terminated merger with Silicon Motion and related arbitration and class action complaint and the risks related to potential payment of damages; the effect of intense and increasing competition; increased tariffs, export controls or imposition of additional trade barriers; impacts of global economic conditions; the cyclical nature of the semiconductor industry; a significant variance in our operating results and impact on volatility in our stock price, and our ability to sustain our current level of revenue, which has previously declined, and/or manage future growth effectively, and the impact of excess inventory in the channel on our customers' expected demand for certain of our products and on our revenue; escalating trade wars, military conflicts and other geopolitical and economic tensions among the countries in which we conduct business; international geopolitical and military conflicts; our ability to obtain or retain government authorization to export certain of our products or technology; the loss of, or a significant reduction in orders from major customers; legal proceedings or potential violations of regulations; information technology failures; a decrease in the average selling prices of our products; failure to penetrate new applications and markets; development delays and consolidation trends in our industry; inability to make substantial and productive research and development investments; delays or expenses caused by undetected defects or bugs in our products; substantial quarterly and annual fluctuations in our revenue and operating results; failure to timely develop and introduce new or enhanced products; order and shipment uncertainties and differences between our estimates of customer demand and product mix and our actual results; failure to accurately predict our future revenue and appropriately budget expenses; lengthy and expensive customer qualification processes; customer product plan cancellations; failure to maintain compliance with government regulations; failure to attract and retain qualified personnel; any adverse impact of rising interest rates on us, our customers, and our distributors and related demand; risks related to compliance with privacy, data protection and cybersecurity laws and regulations; risks related to conforming our products to industry standards; risks related to business acquisitions and investments; claims of intellectual property infringement; our ability to protect our intellectual property; security vulnerabilities of our products; use of open source software in our products; failure to manage our relationships with, or negative

impacts from, third parties; the accuracy of the third-party and internal estimates regarding the size, timing, and growth of the AI server market, the global eFuse market, and the broader power-protection market referenced in this release; our dependence on continued growth in hyperscaler capital spending and AI infrastructure buildout; the timing of product sampling and volume production, including the expectation of volume production in the fourth quarter of 2026, and the risk of delays; our dependence on hyperscalers, OEMs, ODMs, and channel partners to purchase our products; the risk that actual product performance may differ from published specifications; and future decisions relating to our stock repurchase program.

In addition to these risks and uncertainties, investors should review the risks and uncertainties contained in our filings with the Securities and Exchange Commission, including our Current Reports on Form 8-K, as well as the information to be set forth under the caption "Risk Factors" in MaxLinear's Quarterly Report on Form 10-Q for the quarter ended March 31, 2026. All forward-looking statements are based on the estimates, projections and assumptions of management as of the date of this press release, and MaxLinear is under no obligation (and expressly disclaims any such obligation) to update or revise any forward-looking statements whether as a result of new information, future events, or otherwise.

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